#### S80N08R/S/RN/RP

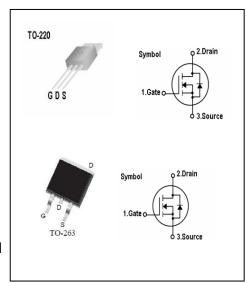
### N-Channel MOSFET

# **Features**

- 80V,80A,Rds(on)(typ)=6.4m $\Omega$  @Vgs=10V
- High Ruggedness
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability

### **General Description**

This Power MOSFET is produced using Si-Tech's advanced Trench MOS Technology. This latest technology has been especially designed to minimize on-state resistance, have a high rugged avalanche characteristics. These devices are well suited for low voltage application such as automotive, DC/DC converters, and high efficiency switch for power management in portable and battery products.



## **Absolute Maximum Ratings**

Symbol	Parameter Value		Units	
VDSS	Drain-Source Voltage 80			
lp	Continuous Drain Current (Tc=25°C)	80	Α	
U	Continuous Drain Current (Tc=100℃)	68	Α	
Ідм	Pulsed Drain Current (Note 1) 320		Α	
Vgs	Gate-Source Voltage ± 25		V	
Eas	Single Pulsed Avalanche Energy (Note 2) 663		mJ	
Po	Maximum Power Dissipation (Tc=25℃)	200	W	
FU	Derating Factor above 25 ℃	1.33	W/℃	
TJ	Operating Junction Temperature Range -55 to +175		$^{\circ}$ C	
Тѕтс	Storage Temperature Range -55 to +175		$^{\circ}$ C	

### Thermal Characteristics

Symbol	Parameter	Max.	Units	
Rth j-c	Thermal Resistance, Junction to case	0.75	°C/W	
Rth c-s	Rth c-s Thermal Resistance, Case to Sink		°C/W	
Rth j-a	Rth j-a Thermal Resistance, Junction to Ambient		°C/W	

- 1 - Mar.2016



### **Si-Tech** SI-TECH SEMICONDUCTOR CO.,LTD

### S80N08R/S/RN/RP

### Electrical Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BVDSS	Drain-Source Breakdown Voltage	Vgs=0V, Id=250uA	80	-	-	V
IDSS	Drain-Source Leakage Current	VDS=78V, VGS=0V	-	-	1	uA
Igss	Gate Leakage Current, Forward	Vgs=25V, Vds=0V	-	-	100	nA
	Gate Leakage Current, Reverse	Vgs=-25V, Vps=0V	-	-	-100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	Vgs=Vps, Ip=250uA	2.5	-	3.5	V
RDS(on)	Drain-Source On-State Resistance	Vgs=10V, Ip=40A	-	6.4	7	m Ω
Qg	Total Gate Charge	VDD=60V	-	110	•	nC
Qgs	Gate-Source Charge	Vgs=10V	-	29	-	nC
Qgd	Gate-Drain Charge	ID=80A (Note 3)	-	52	•	nC
t d(on)	Turn-on Delay Time	VDD=37.5V,VGS=10V	-	26	•	ns
t r	Turn-on Rise Time	$I_D=45A,R_G=4.7\Omega$	-	143		ns
t d(off)	Turn-off Delay Time	Tc=25℃	-	40	•	ns
<b>t</b> f	Turn-off Fall Time	(Note 3)	-	26	•	ns
Ciss	Input Capacitance -	V <sub>DS</sub> =25V	-	3150	-	pF
Coss	Output Capacitance	Vgs=0V	-	456	1	pF
Crss	Reverse Transfer Capacitance	f = 1MHz	-	306	-	pF

### Source-Drain Diode Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Is	Continuous Source Diode Forward Current		-	-	110	Α
lsм	Pulsed Source Diode Forward Current (Note 1)		-	-	320	Α
VsD	Forward On Voltage	Vgs=0V, Is=45A	-	-	1.3	V
<b>t</b> rr	Reverse Recovery Time	Vgs=0V, Is=45A	-	100	150	ns
Qrr	Reverse Recovery Charge	dlF/dt = 100A/us	-	410	650	nC

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=0.5mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25  $\Omega$  , Starting T<sub>J</sub>=25  $^{\circ}$ C
- 3. Pulse Width ≤ 300 us; Duty Cycle≤2%

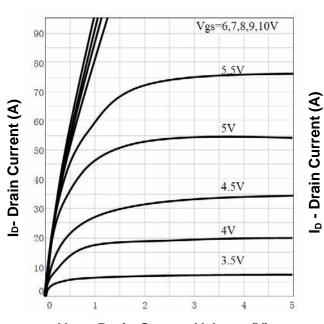
- 2 -Mar.2016



### S80N08R/S/RN/RP

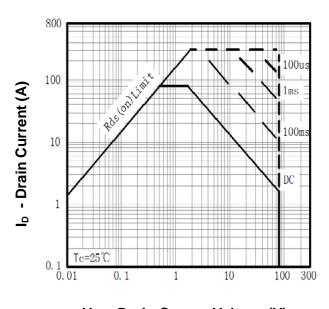
### **Typical Characteristics**





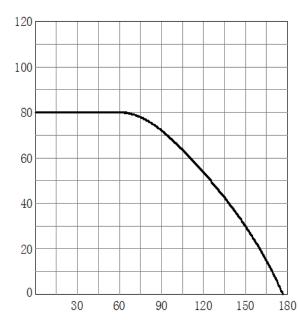
V<sub>DS</sub> - Drain-Source Voltage (V)

#### **Safe Operation Area**



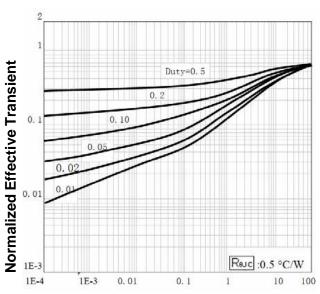
V DS- Drain-Source Voltage (V)

#### **Drain Current**



T<sub>j</sub>- Junction Temperature (°C)

#### **Thermal Transient Impedance**

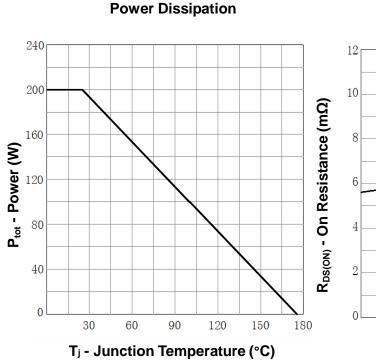


**Square Wave Pulse Duration (sec)** 

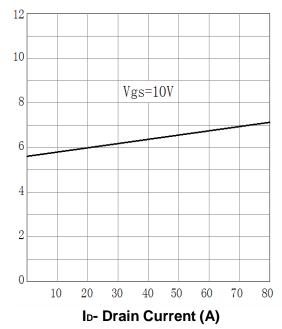
- 3 - Mar.2016

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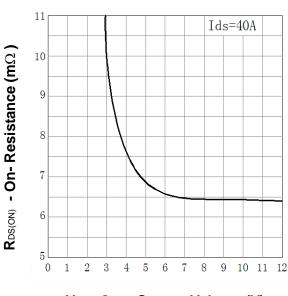
## **Typical Characteristics**



#### **Drain-Source On Resistance**

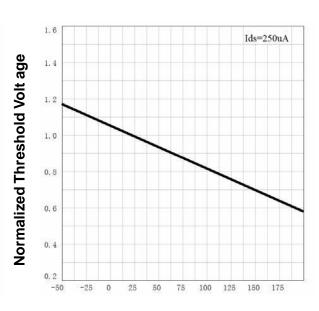


#### **Drain-Source On Resistance**



V<sub>GS</sub> - Gate-Source Voltage (V)

#### **Gate Threshold Voltage**



T<sub>j</sub>- Junction Temperature (°C)

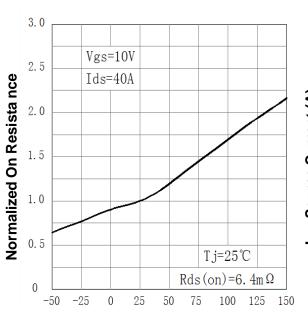
- 4 - Mar.2016



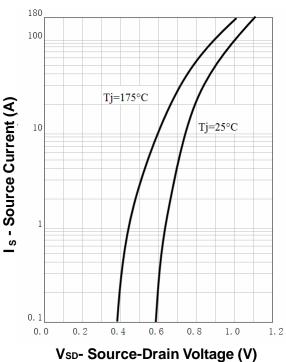
### S80N08R/S/RN/RP

### **Typical Characteristics**

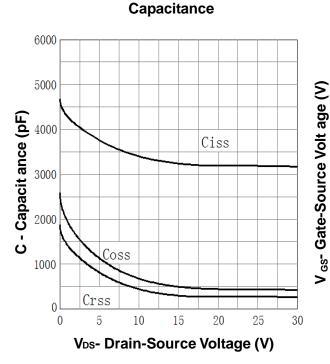


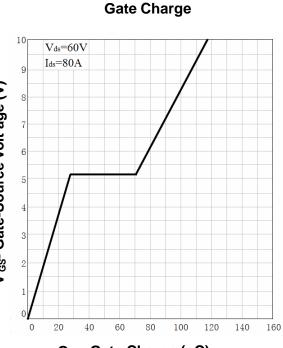


#### **Source-Drain Diode Forward**



T<sub>j</sub>- Junction Temperature (°C)





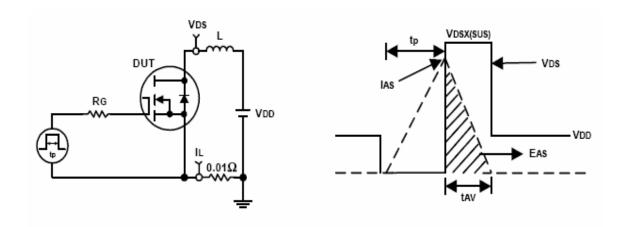
Q<sub>G</sub> - Gate Charge (nC)

Mar.2016 - 5 -

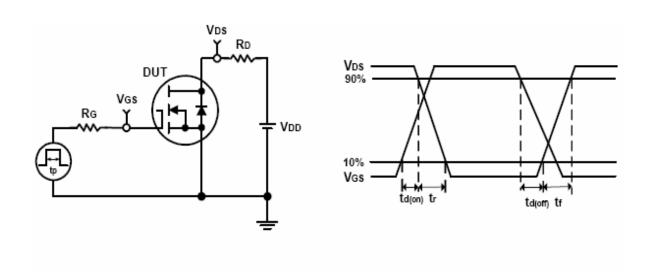


### S80N08R/S/RN/RP

### **Avalanche Test Circuit and Waveforms**



# **Switching Time Test Circuit and Waveforms**



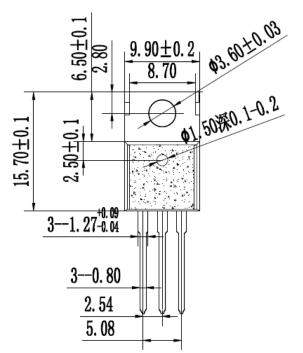
- 6 - Mar.2016

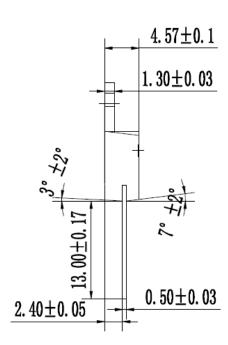
S80N08R/S/RN/RP

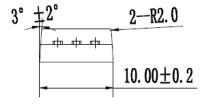
### Package Outline

Dimensions are shown in millimeters

### R: TO220







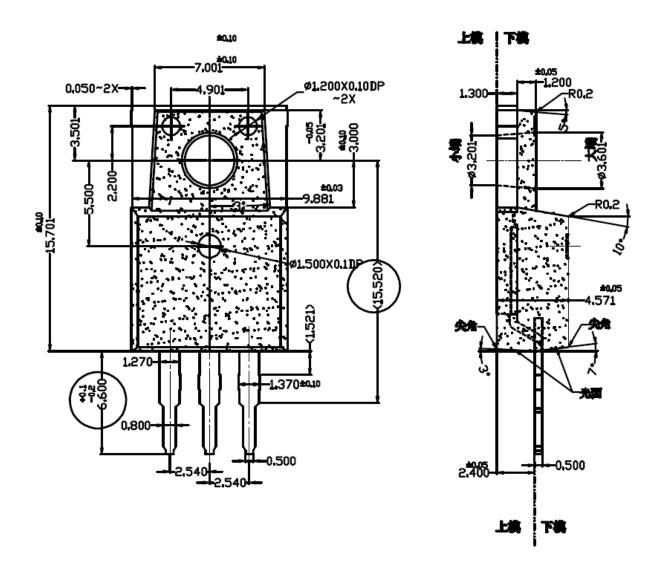
- 7 - Mar.2016



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RN: TO220-SHORT

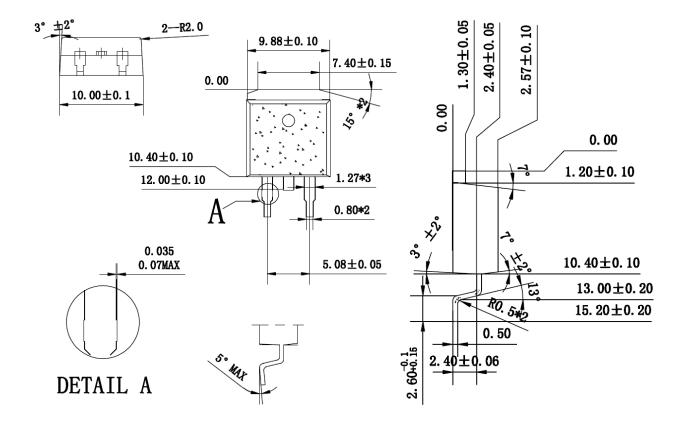


# Si-Tech

# SI-TECH SEMICONDUCTOR CO.,LTD

### S80N08R/S/RN/RP

S: TO263 (D<sup>2</sup>PAK)



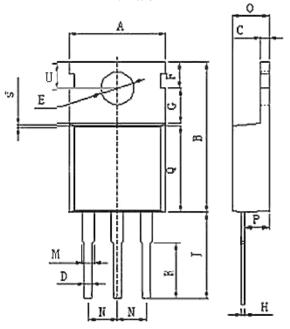
- 9 - Mar.2016

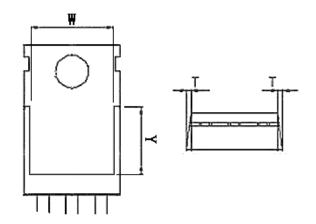
# <u>Si-Tech</u>

# SI-TECH SEMICONDUCTOR CO.,LTD

# S80N08R/S/RN/RP

RP:TO220 (短脚)





DIM	MILLIMETERS
A	10.1 $\pm$ 0.2
В	15.6 $\pm$ 0.2
C	$1.2 \pm 0.2$
D	$0.8 \pm 0.2$
Е	$3.7\pm0.2$
F	$3.0\pm0.2$
G	$3.6 \pm 0.2$
Н	$0.5\pm 0.2$
J	6.5 $\pm$ 0.1
K	$3.5\pm0.1$
M	$1.3\pm 0.2$
N	$2.6\pm0.2$
O	$4.5\pm0.2$
P	$2.0\pm 0.2$
Q	$9.0\pm 0.2$
S	$0.25 \pm 0.1$
T	$0.25\pm0.1$
U	$2.8 \pm 0.07$
W	$8.0\pm0.2$
Y	$6.4\pm0.2$

(单位: mm)